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Submission Guidelines

The content must be novel and original, previously unpublished, non-confidential and without commercial content.

All abstracts and proposals must be submitted electronically to our website by 4 October 2021. Get more details in the call for papers here. Selected authors and instructors will be announced by 11 December 2021. The first 100 people to submit abstracts will be entered into a drawing to win a free ECTC 2022 registration.

Abstracts

All accepted papers will be presented during oral, interactive presentations or special student poster sessions. Abstracts must have 250-750 words. Please start your abstract with a first paragraph of no more than 50 words to clearly highlight and summarize the novelty of your work.
For more information, contact:
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TU Dresden
Email: karlheinz.bock@tu-dresden.de

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